

**ORGANISATION MONDIALE  
DU COMMERCE**

**ORGANIZACIÓN MUNDIAL  
DEL COMERCIO**

**WORLD TRADE ORGANIZATION**

Centre William Rappard  
Rue de Lausanne 154  
Case postale  
CH - 1211 Genève 21

Téléphone: (41 22) 739 51 11  
Ligne directe: (41 22) 739 52 52  
Téléfax: (41 22) 731 42 06  
Télex: 412 324 OMC/WTO CH  
Télégramme: OMC/WTO, GENÈVE

Référence: WLI/200

17 April 1997

**MARRAKESH AGREEMENT ESTABLISHING  
THE WORLD TRADE ORGANIZATION  
DONE AT MARRAKESH ON 15 APRIL 1994**

**MARRAKESH PROTOCOL TO THE  
GENERAL AGREEMENT ON TARIFFS AND TRADE 1994**

**CERTIFICATION OF MODIFICATIONS AND RECTIFICATIONS  
TO SCHEDULE XXXVIII - JAPAN**

**TRANSMISSION OF CERTIFIED TRUE COPY**

I have the honour to furnish herewith a certified true copy of the Certification of Modifications and Rectifications to Schedule XXXVIII-Japan, done at Geneva on 7 April 1997.

R. Ruggiero  
Director-General

WT/Let/138

SCHEDULES OF TARIFF CONCESSIONS TO THE  
GENERAL AGREEMENT ON TARIFFS AND TRADE 1994

CERTIFICATION OF MODIFICATIONS AND RECTIFICATIONS

**SCHEDULE XXXVIII - JAPAN**

WHEREAS the CONTRACTING PARTIES to the General Agreement on Tariffs and Trade 1947 adopted, on 26 March 1980, a Decision on Procedures for Modification and Rectification of Schedules of Tariff Concessions (BISD 27S/25);

WHEREAS in accordance with the provisions of the above-mentioned Decision, the drafts containing modifications and rectifications to Schedule XXXVIII - Japan were communicated to all Members in documents G/MA/TAR/RS/10 and G/MA/TAR/RS/10/Corr.1, and G/MA/TAR/RS/12 and G/MA/TAR/RS/12/Corr.1 and were approved on 23 March 1997 and 7 April 1997, respectively;

IT IS HEREBY CERTIFIED that the modifications and rectifications to Schedule XXXVIII - Japan are established in conformity with the above-mentioned Decision.

The annexed modifications and rectifications to the Schedule become effective in accordance with the notification given to that effect by the Government of Japan to the Director-General of the World Trade Organization (hereinafter referred to as the "WTO") upon completion of Japan's internal procedures.

This Certification is deposited with the Director-General of the WTO, who shall promptly furnish a certified true copy thereof to each Member of the WTO. It shall be registered in accordance with the provisions of Article 102 of the Charter of the United Nations.

DONE at Geneva this seventh day of April, one thousand nine hundred and ninety-seven.

R. Ruggiero

Certified true copy:

Director-General

MODIFICATIONS AND RECTIFICATIONS TO SCHEDULE XXXVIII - JAPAN

SCHEDULE XXXVIII - JAPAN

NOTES TO SCHEDULE XXXVIII - JAPAN

Sub-paragraph 1(a) shall be replaced by the following :

"(a) Part I Most-Favoured-Nation Tariff  
Section I Agricultural Products  
Section I-A Tariffs  
Section I-B Tariff Quotas  
Section II Other Products  
Attachment I to Section II of Part I  
Attachment II to Section II of Part I"

PART I MOST-FAVOURLED-NATION TARIFF  
SECTION II Other Products

Notes to Section II of Part I

Delete "the Attachment to this Section" in paragraph 13 and substitute "the Attachment I to this Section".

PART I MOST-FAVORED-NATION TARIFF  
SECTION II Other Products

Mark the tariff item number 2918.13 with a letter "P".

For the tariff item numbers 2841.10, 2903.22, 2903.30, 2903.51, 2906.21, 2915.29, 2922.42, 3102.70, 3904.61, 3907.20, 3907.60, 3908.10, 3910.00, 3912.20 and 3912.31, delete a letter "P"

Replace "Attachment to Section II of Part I" by "Attachment I to Section II of Part I", and insert the following Attachment after Attachment to Section II of Part I (to become Attachment I to Section II of Part I).

Attachment II to Section II of Part I

Notes to Attachment II to Section II of Part I

1. Notwithstanding the provision of paragraph 3 of the Notes to the Schedule, the tariff reductions from the bound rate as of 1 January 1997 to free in respect of all products classified (or classifiable) in the tariff item numbers in List I shall be implemented in three equal rate reductions as follows :
  - (a) The first reduction shall be implemented on the date that this instrument becomes effective;
  - (b) The second reduction shall be implemented on 1 January 1998;
  - (c) The third reduction shall be implemented on 1 January 1999.
  
2. Notwithstanding the provision of paragraph 3 of the Notes to the Schedule, the tariff reductions from the bound rate as of 1 January 1997 to free in respect of all products classified (or classifiable) in the tariff item numbers in List II shall be implemented in four equal rate reductions as follows :
  - (a) The first reduction shall be implemented on the date that this instrument becomes effective;
  - (b) The second reduction shall be implemented on 1 January 1998;
  - (c) The third reduction shall be implemented on 1 January 1999;
  - (d) The fourth reduction shall be implemented on 1 January 2000.  
Of the products classified (or classifiable) in the tariff item numbers marked with an asterisk ("\*"), only those of a kind used for telecommunications are covered by the tariff reduction.

3. Notwithstanding the provision of paragraph 3 of the Notes to the Schedule, the tariff reductions from the bound rate as of 1 January 1997 to free in respect of the products in Lists III and IV, wherever they are classified, shall be implemented in three equal rate reductions as follows :
  - (a) The first reduction shall be implemented on the date that this instrument becomes effective;
  - (b) The second reduction shall be implemented on 1 January 1998;
  - (c) The third reduction shall be implemented on 1 January 1999.
4. Rounding of the rates after each reduction implemented pursuant to paragraphs 1-3 above shall be subject to the provisions in paragraph 5 of the Notes to the Schedule.

List I

8421.91, 8424.89, 8424.90, 8464.20, 8464.90, 8466.91, 8466.93, 8469.11, 8470.10, 8470.21, 8470.29, 8470.30, 8470.90, 8471.10, 8471.30, 8471.41, 8471.49, 8471.50, 8471.60, 8471.70, 8471.80, 8471.90, 8473.21, 8473.29, 8473.30, 8473.50, 8480.71, 8504.40, 8504.50, 8518.10, 8518.29, 8518.30, 8520.20, 8523.90, 8524.31, 8524.39, 8524.40, 8524.91, 8524.99, 8525.40, 8532.10, 8533.10, 8533.21, 8533.29, 8533.31, 8533.39, 8533.40, 8536.50, 8541.10, 8541.21, 8541.29, 8541.30, 8541.40, 8541.50, 8541.60, 8542.12, 8542.13, 8542.14, 8542.19, 8542.30, 8542.40, 8542.50, 8542.90, 8543.11, 8544.70, 9026.10, 9026.20, 9026.80, 9026.90, 9027.30, 9027.80, 9027.90, 9030.90, 9031.41, 9031.49, 9031.90

List II

3818.00, 8544.41 \* , 8544.49 \* , 8544.51 \*

### List III <sup>1</sup>

Quartz reactor tubes and holders designed for insertion into diffusion and oxidation furnaces for production of semiconductor wafers

Chemical vapor deposition apparatus for semiconductor production

Parts of chemical vapor deposition apparatus for semiconductor production

Apparatus for stripping or cleaning semiconductor wafers

Lasercutters for cutting contacting tracks in semiconductor production by laser beam

Machines for sawing monocrystal semiconductor boules into slices, or wafers into chips

Parts for machines for sawing monocrystal semiconductor boules into slices, or wafers into chips

Parts of dicing machines for scribing or scoring semiconductor wafers

Parts of lasercutters for cutting contacting tracks in semiconductor production by laser beam

Parts of apparatus for stripping or cleaning semiconductor wafers

Encapsulation equipment for assembly of semiconductors

Parts of encapsulation equipment

Automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices

Apparatus for physical deposition by sputtering on semiconductor wafers

Apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays

Die attach apparatus, tape automated bonders, and wire bonders for assembly of semiconductors

Machines for bending, folding and straightening semiconductor leads

Physical deposition apparatus for semiconductor production

Spinners for coating photographic emulsions on semiconductor wafers

Parts of apparatus for physical deposition by sputtering on semiconductor wafers

Parts for die attach apparatus, tape automated bonders, and wire bonders for assembly of semiconductors

Parts for spinners for coating photographic emulsions on semiconductor wafers

Parts of apparatus for wet etching, developing, stripping or cleaning semiconductor wafers and flat panel displays

Parts of automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices

Parts of encapsulation equipment for assembly of semiconductors

Parts of machines for bending, folding and straightening semiconductor leads

Parts of physical deposition apparatus for semiconductor production

Apparatus for rapid heating of semiconductor wafers

Parts of apparatus for rapid heating of wafers

Wafer probers

Optical stereoscopic microscopes fitted with equipment specifically designed for the handling and transport of semiconductor wafers or reticles